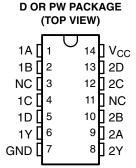
- Qualified for Automotive Applications
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive up to Ten LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}
- Typical t_{pd} = 11 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max



description/ordering information

This device contains two independent 4-input AND gates. It performs the Boolean function $Y = A \bullet B \bullet C \bullet D$ or $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$ in positive logic.

ORDERING INFORMATION[†]

T _A	PACKA	GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
40°C to 405°C	SOIC - D	Reel of 2500	SN74HC21QDRQ1	HC21Q
-40°C to 125°C	TSSOP - PW	Reel of 2000	SN74HC21QPWRQ1	HC21Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each gate)

	INP	OUTPUT		
Α	В	С	D	Υ
Н	Н	Н	Н	Н
L	X	X	X	L
Х	L	X	X	L
Χ	Χ	L	X	L
Χ	Χ	Χ	L	L

logic diagram (positive logic)







Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT	
V_{CC}	Supply voltage		2	5	6	V	
		V _{CC} = 2 V	1.5				
V_{IH}	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			V	
		V _{CC} = 6 V	4.2				
		V _{CC} = 2 V			0.5		
V_{IL}	Low-level input voltage	V _{CC} = 4.5 V			1.35	V	
		V _{CC} = 6 V			1.8		
VI	Input voltage		0		V_{CC}	V	
Vo	Output voltage		0		V_{CC}	V	
		V _{CC} = 2 V			1000		
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 \text{ V}$			500	ns	
		V _{CC} = 6 V			400		
T _A	Operating free-air temperature		-40		125	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		T _A = -40°C TO 85°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
V _{OH}	$V_i = V_{iH}$ or V_{iL}		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
		I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	v
	V _I = V _{IH} or V _{IL}		4.5 V		0.001	0.1		0.1		0.1	
V _{OL}			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
l _l	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			2		40		20	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

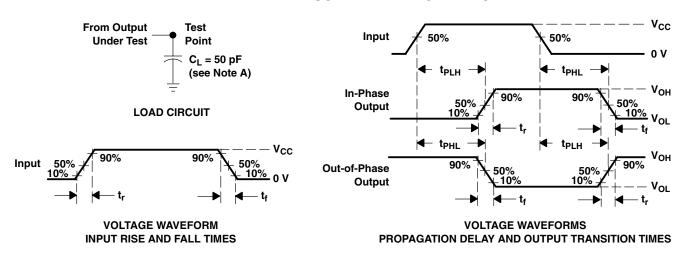
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	v _{cc}	T _A = 25°C			T _A = -		T _A = -40°C TO 85°C		UNIT
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	A, B, C, or D		2 V		44	110		165		140	
t _{pd}		Y	4.5 V		14	22		33		28	ns
			6 V		11	19		28		24	
			2 V		29	75		110		95	
t _t		Υ	4.5 V		10	15		22		19	ns
			6 V		8	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	25	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns. $t_f = 6$ ns.
- C. The outputs are measured one at a time, with one input transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74HC21QDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(HC21Q, HC21Q1)	Samples
SN74HC21QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(HC21Q, HC21Q1)	Samples
SN74HC21QPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(HC21Q, HC21Q1)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74HC21-Q1:

Catalog: SN74HC21

Military: SN54HC21

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC21QDRQ1	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC21QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC21QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC21QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC21QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC21QDRQ1	SOIC	D	14	2500	356.0	356.0	35.0
SN74HC21QPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HC21QPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HC21QPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HC21QPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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